



Material Content Data Sheet



Sales Product Name		BSS214N H6327		Issued		29. August 2013		
MA#		MA000938692						
Package		PG-SOT23-3-5		Weight*		9.36 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.008	0.09		857	
	non noble metal	tin	7440-31-5	0.002	0.02		221	
	inorganic material	silicon	7440-21-3	0.122	1.31	1.42	13070	14148
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		966	
	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		322	
	non noble metal	copper	7440-50-8	3.000	32.06	32.20	320572	321924
wire	non noble metal	copper	7440-50-8	0.044	0.47	0.47	4741	4741
encapsulation	organic material	carbon black	1333-86-4	0.057	0.61		6128	
	plastics	epoxy resin	-	1.233	13.18		131754	
	inorganic material	silicondioxide	60676-86-0	4.445	47.48	61.27	474929	612811
leadfinish	non noble metal	tin	7440-31-5	0.150	1.60	1.60	15988	15988
plating	noble metal	silver	7440-22-4	0.284	3.04	3.04	30388	30388
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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